PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT7226277

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
XI ZENG	03/15/2022
PU ZHOU	03/15/2022
HUIJIE YAN	03/15/2022
YING LUO	03/15/2022
XUEHONG HE	03/15/2022
YUAN ZHANG	03/15/2022
HAILING YANG	03/15/2022
XIAMENG LIAN	03/15/2022

RECEIVING PARTY DATA

Name:	SHANGHAI IC R&D CENTER CO., LTD.
Street Address:	497 GAOSI ROAD, ZHANGJIANG HIGH-TECH PARK, PUDONG
City:	SHANGHAI
State/Country:	CHINA
Postal Code:	201210
Name:	CHENGDU IMAGE DESIGN TECHNOLOGY CO.,LTD.
Street Address:	NO.22-23, FLOOR 3, BUILDING 1, NO.1268 TIANFU AVENUE, HIGH-TECH ZONE
City:	CHENGDU
State/Country:	CHINA
Postal Code:	610041

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17760767

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 8615216606233

Email: ivan@tianchen-ip.com

Correspondent Name: TIANCHEN LLC.

PATENT

507179431 REEL: 059274 FRAME: 0792

	3302 TOWER1, NO.388 ZHONGJIANG ROAD, PUT SHANGHAI, CHINA 200062	
NAME OF SUBMITTER:	YUAN R. LI	
SIGNATURE:	/Yuan R. Li/	
DATE SIGNED:	03/16/2022	
	This document serves as an Oath/Declaration (37 CFR 1.63).	

Total Attachments: 3

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> PATENT REEL: 059274 FRAME: 0793

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:

METHOD OF REMOVING FIXED PATTERN NOISE

for which I/We executed an application for United States Letters Patent concurrently herewith or filed
an application for United States Letters Patent on(Application No); and
(1 pp 10 at
WHEREAS, SHANGHAI IC R&D CENTER CO., LTD., a corporation of P.R. China whose
post office address is No.497, Gaosi Road, Zhangjiang High-Tech Park, Pudong, Shanghai, China
201210 and CHENGDU IMAGE DESIGN TECHNOLOGY CO.,LTD., a corporation of P.R. China
whose post office address is No.22-23, Floor 3, Building 1, No.1268 Tianfu Avenue, High-Tech Zone
Chengdu, Sichuan, China 610041 (hereinafter referred to as Assignees), and are desirous of securing the
entire right, title, and interest in and to this invention in all countries throughout the world, and in and
to the application for United States Letters Patent on this invention and the Letters Patent to be issued
upon this application;
NOW THEREFORE, be it known that, for good and valuable consideration the receipt of
which from Assignees is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred,
and set over, and do hereby sell, assign, transfer, and set over unto the Assignees, its lawful successors
and assigns, my/our entire right, title, and interest in and to this invention, provisional Application
No, filed (if any), and this application, and all divisions, and continuations
thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof,
and all rights to claim priority on the basis of the above provisional application (if any), as well as all
rights to claim priority on the basis of this application, and all applications for Letters Patent which may
hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/WE have not executed and will not execute any agreement in conflict with this Assignment;

terms of this Assignment;

on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignees, its successors and assigns, in accordance with the

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with Assignees, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignees, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignees, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignees, its successors and assigns.

PATENT REEL: 059274 FRAME: 0794

N TESTIMONY VVHEREOF, I/VVe have her		DATE
1. FULL NAME OF FIRST ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
Zeng, Xi	Zeng Xi	
MAILING ADDRESS c/o No.497, Gaosi Road, Zhangjiang High-Tech Park, Pudong, Shanghai, China 201210		RESIDENCE Shanghai, China
2. FULL NAME OF FIRST ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
Zhou, Pu	Than Pu	
MAILING ADDRESS c/o No.497, Gaosi Road, Zhangjiang High-Tec	, ,	RESIDENCE Shanghai, China
		1 DO OTH
3. FULL NAME OF FIRST ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
Yan, Huijie	Yan Huijic	DESIDENCE
MAILING ADDRESS c/o No.497, Gaosi Road, Zhangjiang High-Teo	ch Park, Pudong, Shanghai, China 201210	RESIDENCE Shanghai, China
4. FULL NAME OF FIRST ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
Luo, ying	Luo, ying	RESIDENCE
MAILING ADDRESS c/o No.497, Gaosi Road, Zhangjiang High-Tech Park, Pudong, Shanghai, China 201210		Shanghai, China
5. FULL NAME OF FIRST ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
He, Xuehong	He, Xuehong	
MAILING ADDRESS c/o No.497, Gaosi Road, Zhangjiang High-Tech Park, Pudong, Shanghai, China 201210		RESIDENCE Shanghai, China
6. FULL NAME OF FIRST ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
Zhang, Yuan	zhang. Yuah	, <u></u>
MAILING ADDRESS c/o No.497, Gaosi Road, Zhangjiang High-Te	ch Park, Pudong, Shanghai, China 201210	RESIDENCE Shanghai, China
7. FULL NAME OF FIRST ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
Yang, Hailing	Yang, Hailing	
MAILING ADDRESS c/o No.497, Gaosi Road, Zhangjiang High-Te	3	RESIDENCE Shanghai, China

8. FULL NAME OF FIRST ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
Lian, Xiameng	Lian, Xiameng	
MAILING ADDRESS c/o No.497, Gaosi Road, Zhangjiang High-Tech Park, Pudong, Shanghai, China 201210		RESIDENCE Shanghai, China

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